

This Page Is Inserted by IFW Operations  
and is not a part of the Official Record

## **BEST AVAILABLE IMAGES**

Defective images within this document are accurate representations of the original documents submitted by the applicant.

Defects in the images may include (but are not limited to):

- BLACK BORDERS
- TEXT CUT OFF AT TOP, BOTTOM OR SIDES
- FADED TEXT
- ILLEGIBLE TEXT
- SKEWED/SLANTED IMAGES
- COLORED PHOTOS
- BLACK OR VERY BLACK AND WHITE DARK PHOTOS ✓
- GRAY SCALE DOCUMENTS

**IMAGES ARE BEST AVAILABLE COPY.**

**As rescanning documents *will not* correct images,  
please do not report the images to the  
Image Problem Mailbox.**

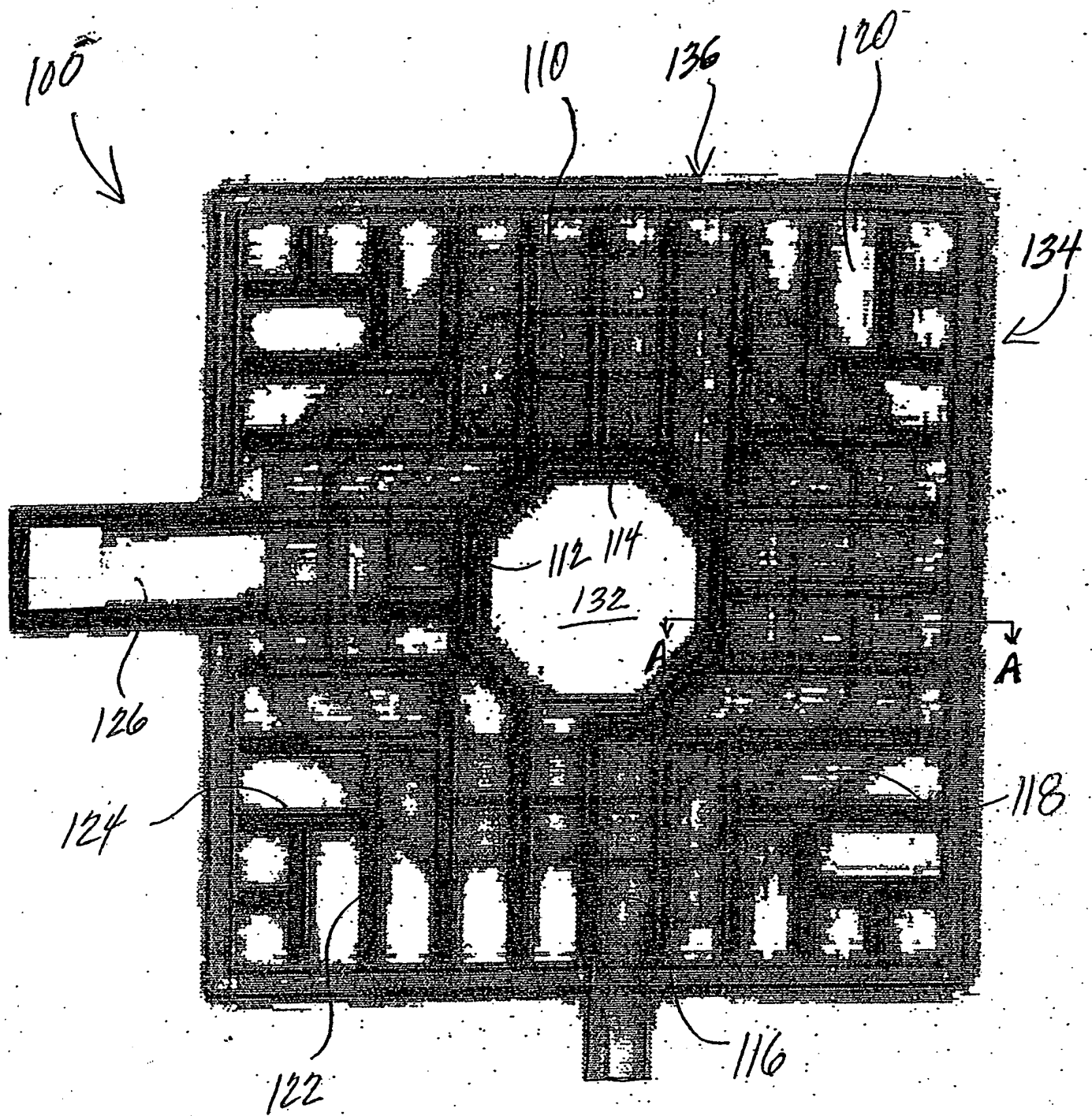


FIG. 1

200  
FORM FIRST DIELECTRIC LAYER OVER SEMICONDUCTOR SUBSTRATE

~202

FORM FIRST MAGNETIC LAYER OVER FIRST DIELECTRIC LAYER

~204

PATTERN FIRST MAGNETIC LAYER TO DEFINE AT LEAST ONE SLOT

~206

FORM SECOND DIELECTRIC LAYER OVER FIRST MAGNETIC LAYER,  
FILLING EACH SLOT IN FIRST MAGNETIC LAYER

~208

PATTERN SECOND DIELECTRIC LAYER  
TO DEFINE AT LEAST ONE VIA TO FIRST MAGNETIC LAYER

~210

FORM CONDUCTIVE LAYER OVER SECOND DIELECTRIC LAYER

~212

PATTERN CONDUCTIVE LAYER  
TO FORM A CONDUCTOR HAVING A SPIRAL-SHAPED SIGNAL PATH  
AND TO CLEAR ANY VIAS TO FIRST MAGNETIC LAYER

~214

FORM THIRD DIELECTRIC LAYER OVER CONDUCTIVE LAYER

~216

PATTERN THIRD DIELECTRIC LAYER  
TO DEFINE AT LEAST ONE VIA TO FIRST MAGNETIC LAYER

~218

FORM SECOND MAGNETIC LAYER OVER THIRD DIELECTRIC LAYER,  
FILLING ANY VIAS TO FIRST MAGNETIC LAYER

~220

PATTERN SECOND MAGNETIC LAYER TO FORM AT LEAST ONE SLOT

~222

FIG. 2

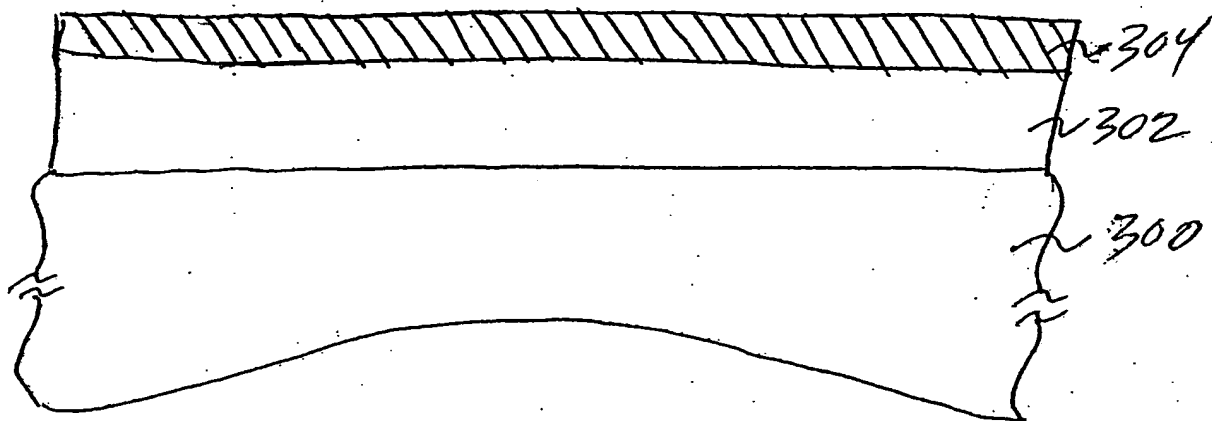


FIG. 3

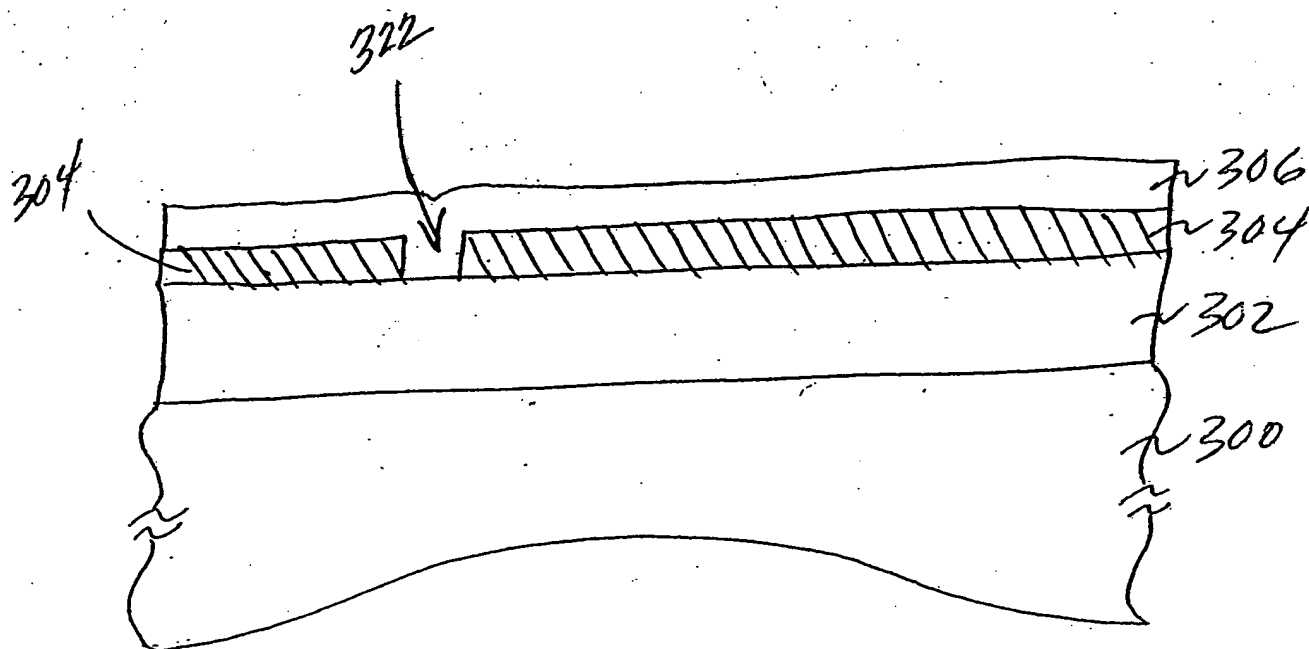


FIG. 4

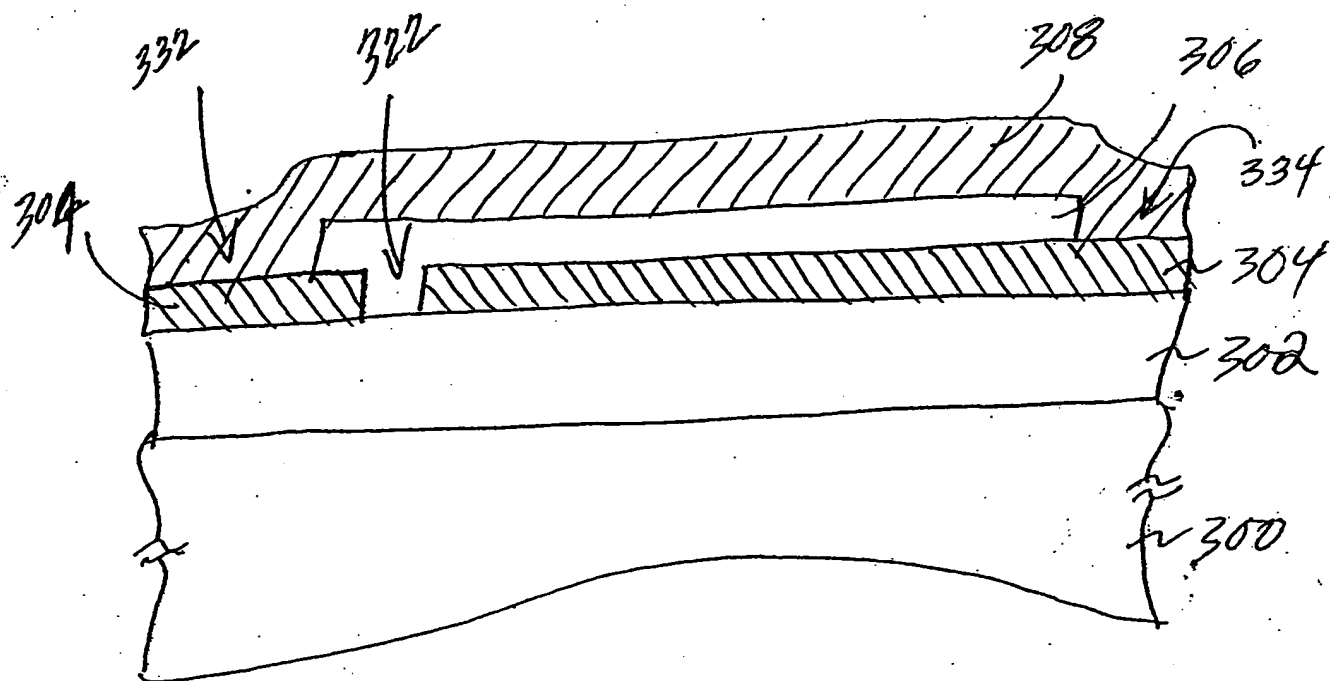


FIG. 5

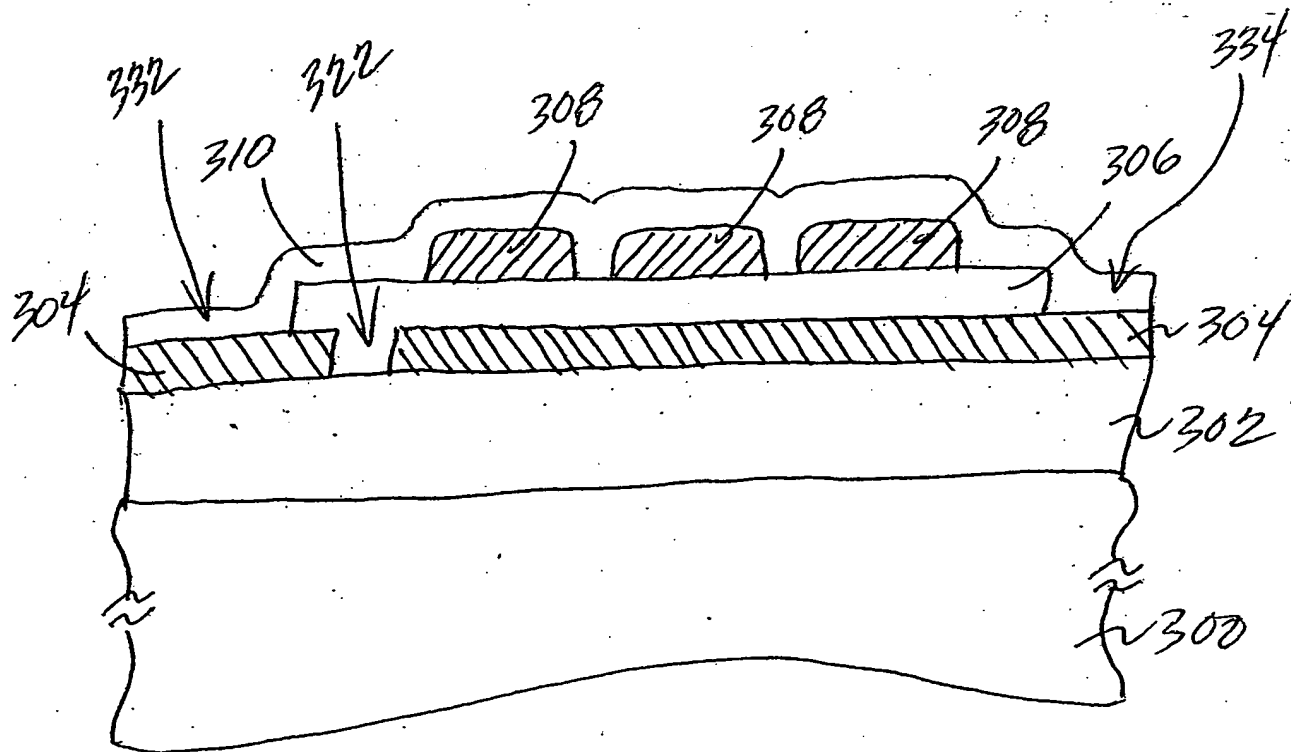


FIG. 6

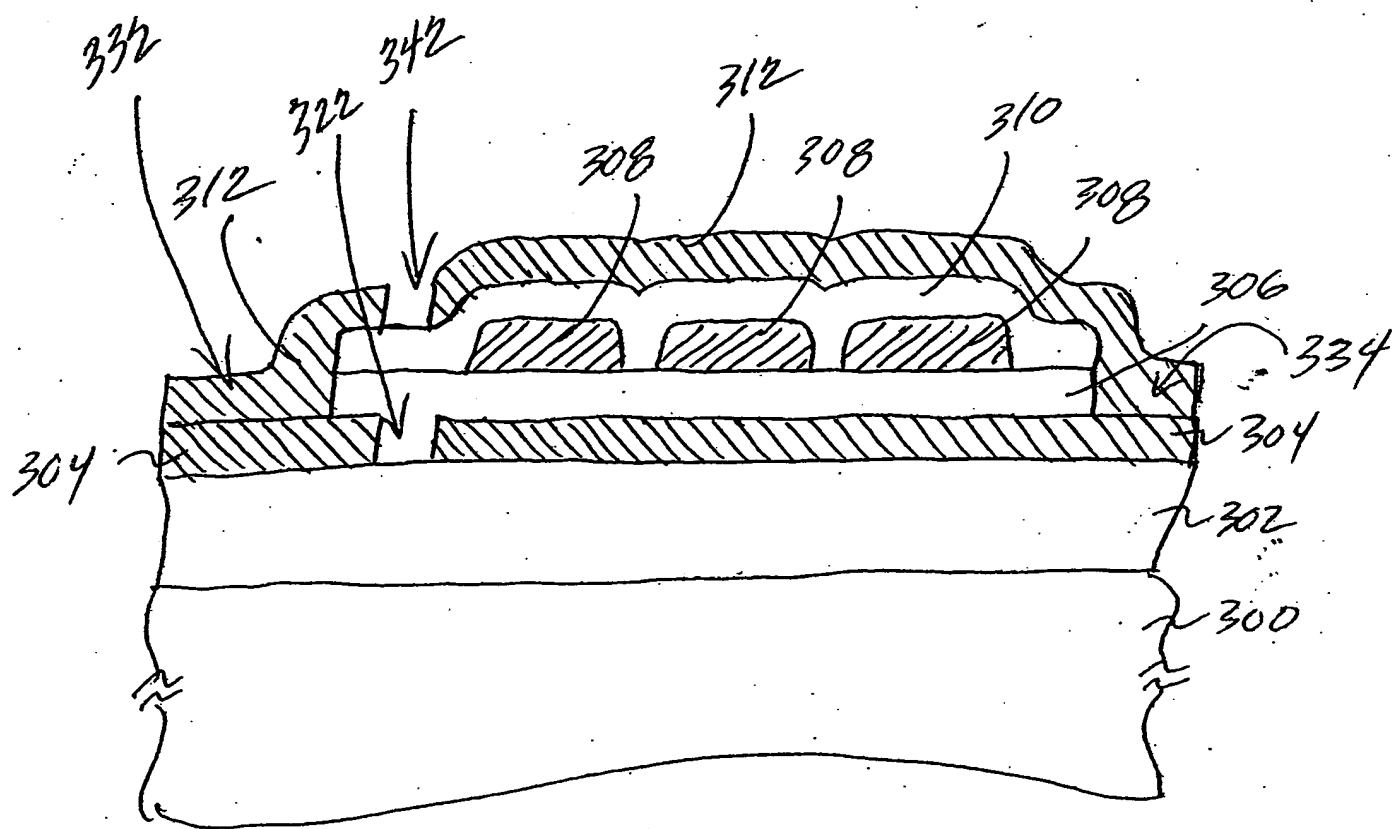


FIG. 7

900

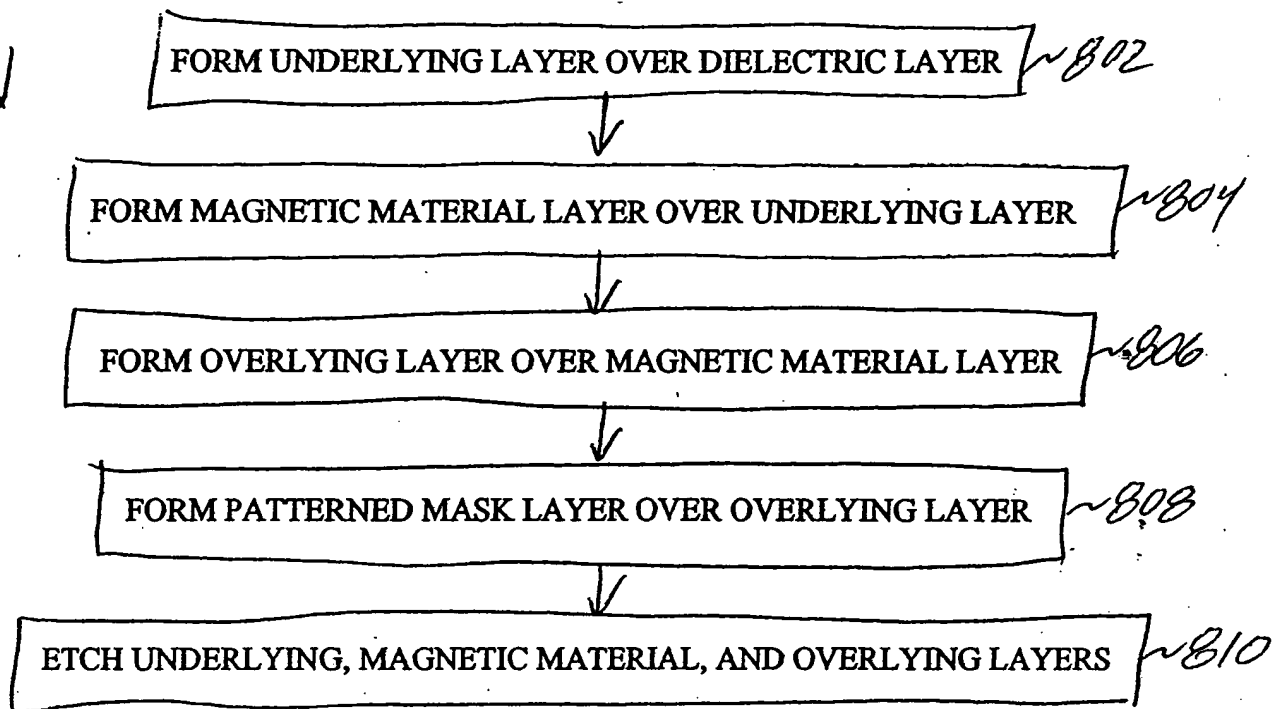


FIG. 8

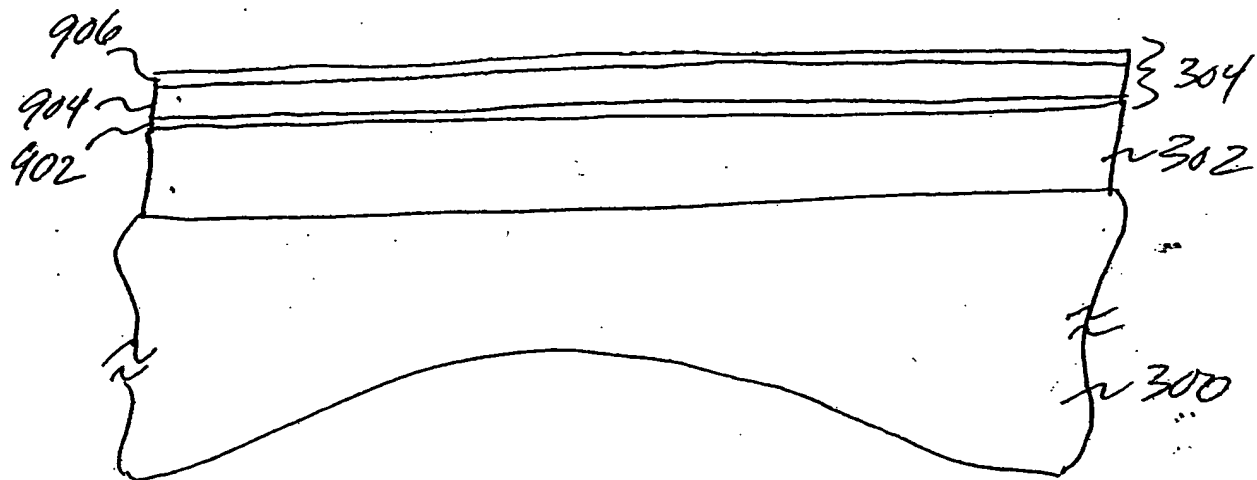


FIG. 9

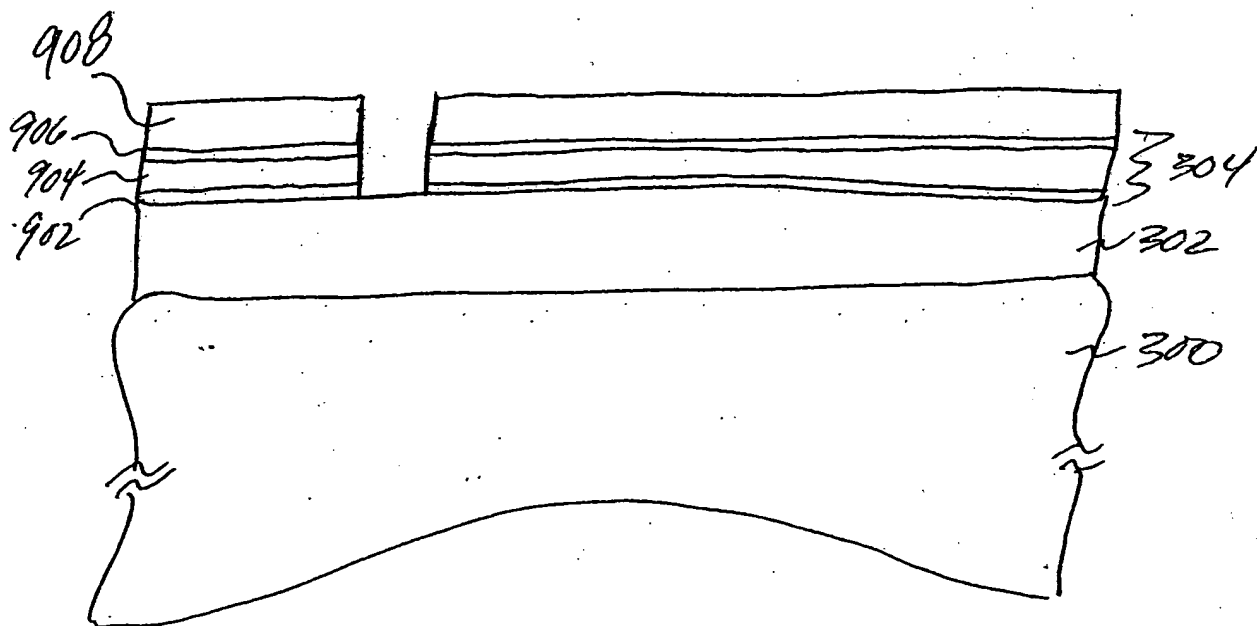


FIG. 10



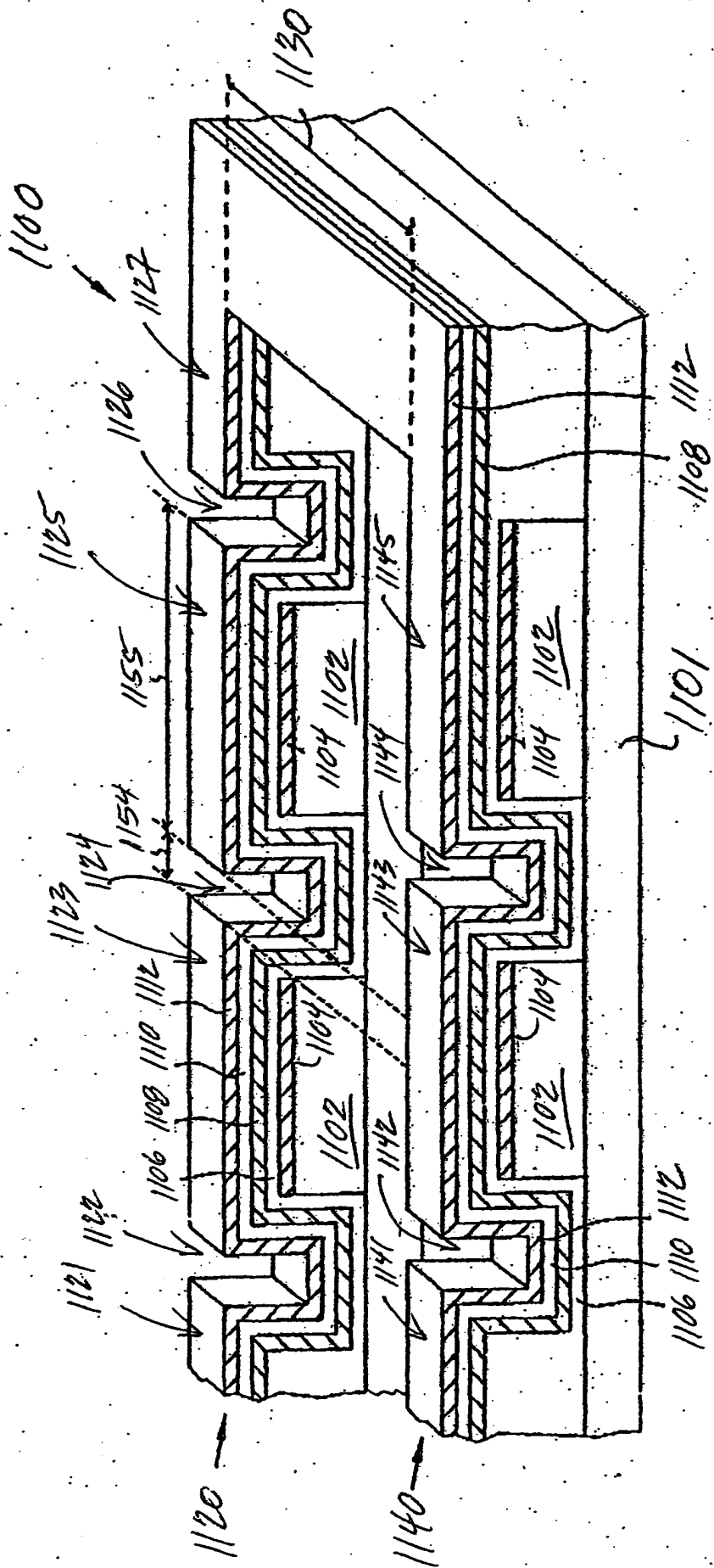


FIG. 11

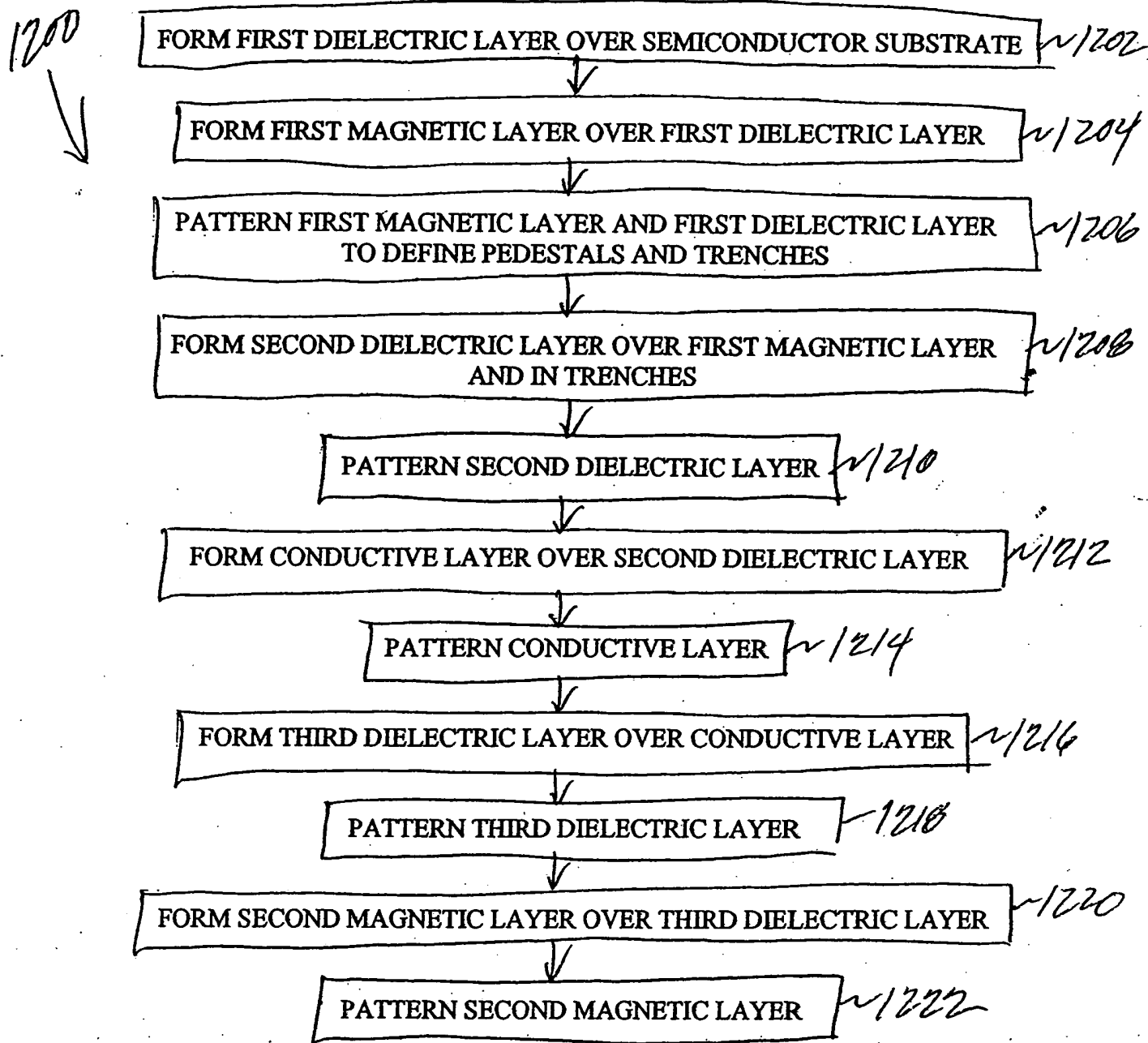


FIG. 12

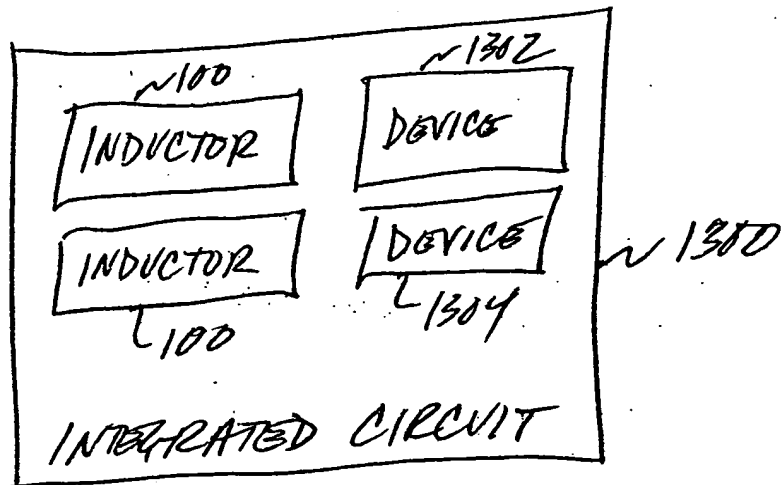


FIG. 13

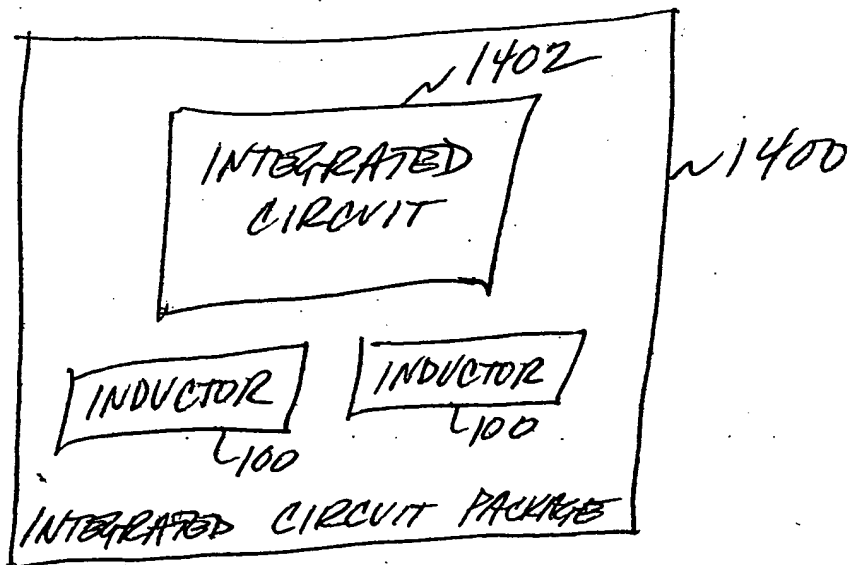


FIG. 14